B) Please replace the indicated claims as follows:

1. (Amended) A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:

a rotating polishing material having an upwardly facing polishing surface for polishing a substrate thereon;

an arm having a delivery portion disposed at least partially over the polishing surface;

a first nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a first rate; and

at least a second nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a second rate that is different than the first rate; wherein the first nozzle dispenses a greater volume of polishing fluid on a first portion of the polishing surface as it interfaces with the substrate than the polishing fluid of equal concentration dispensed on a second portion of the polishing surface by the second nozzle.

16. (Amended) A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:

a polishing surface adapted to polishing a substrate in contact therewith;

an arm having a delivery portion disposed at least partially over the polishing surface;

a first means for providing polishing fluid to the polishing surface at a first rate; and

a second means for providing polishing fluid to the polishing surface at a second rate, wherein the first means flows a greater volume of polishing fluid on a first portion of the polishing surface as it interfaces with the substrate than the polishing fluid of equal concentration disposed on a second portion of the polishing surface by the second means.

19. (AMENDED) A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:

a platen supporting the polishing surface;

a polishing head disposed over the platen and adapted to hold a substrate against the polishing surface;

an arm having a delivery portion disposed at least partially over the polishing surface;

a first nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a first rate to a first portion of the polishing surface; and

at least a second nozzle disposed on the delivery portion and adapted to flow the polishing fluid at a second rate that is different than the first rate to a second portion of the polishing surface, wherein the polishing fluid flowed on the first portion has a greater volume as it interfaces with the substrate than the polishing fluid of equal concentration flowed on the second portion by the second nozzle.

23. (AMENDED) A method of supplying a polishing fluid to a chemical mechanical polishing surface comprising:

flowing polishing fluid onto a rotating polishing pad at a first location at a first rate; and

flowing polishing fluid of equal concentration on the polishing pad at a second location at a second rate that is different than the first rate, wherein the polishing fluid disposed on the first portion has a greater volume as it interfaces with a substrate being polished than the polishing fluid disposed on the second portion.

C) Please add the following new claims:

30. (New) A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:

a rotating polishing material having an upwardly facing polishing surface for polishing a substrate thereon;

an arm having a delivery portion disposed at least partially over the polishing surface;

a first nozzle coupled to the delivery portion and supported over a first zone defined on the polishing material by a volume of polishing fluid provided by the first nozzle; and

at least a second nozzle coupled to the delivery portion and supported over a second zone defined on the polishing material by a volume of polishing fluid provided by the second nozzle that is different than the volume provided to the first zone, wherein the polishing fluid in the first zone and the second zone have equal concentration when rotated into contact the substrate.

31. (New) A system for delivering a polishing fluid to a chemical mechanical polishing surface comprising:

a rotating polishing material having an upwardly facing polishing surface for polishing a substrate thereon;

a first zone defined on the polishing material having a first volume of polishing fluid disposed thereon;

a second zone defined on the polishing material radially inward of the first zone and having a volume of polishing fluid disposed thereon that is different than a volume of polishing fluid of the same concentration disposed on the first zone when contacting the substrate positioned on the polishing material; and

an arm having a first nozzle and a second nozzle coupled thereto, the first nozzle positioned to deliver a first flow of polishing fluid to the first zone, and the second nozzle positioned to deliver a second flow of polishing fluid to the second zone that is different than the first flow.

32. (New) The system of claim 31 further comprising a flow control device coupled to at least one of the first or second nozzles.

33. (New) The system of claim 32, wherein the flow control device is a flow control selected from the group consisting of orifices, needle valves, proportional valves, pinch valves, restrictors, mass flow controllers and metering pumps.

34. (New) The system of claim 31, wherein the arm further comprises a polishing fluid delivery line disposed within the arm coupling the first and second nozzles.

35. (New) The system of claim 31 further comprising a first fluid source coupled to the first nozzle and a second fluid source coupled to the second nozzle.

36. (New) The system of claim 31 further comprising a plurality of independently controllable nozzles coupled between the first and second nozzles, the independently controllable nozzles adapted to flow polishing fluid at a controlled rate.

37. (New) The system of claim 31, wherein first flow is at least 1.15 times the second flow rate.

38. (New) The system of claim 31, wherein first flow is about 1.2 to about 20 times the second flow rate.

39. (New) The system of claim 31 further comprising a metrology device adapted to provide information utilized to control at least one of the flows through the nozzles.–.

REMARKS

This response is intended as a full and complete response to the Office Action dated October 29, 2002. In view of the following discussion, the Applicants believe that all claims are in allowable form.